

Notice of References Cited	Application/Control No. 10/582,295		Applicant(s)/Patent Under Reexamination VIVIENNE ET AL.	
	Examiner BOBBY RAMDHANIE		Art Unit 1797	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-6,273,478	08-2001	Benett et al.	285/346
	B	US-			
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	E	US-			
	F	US-			
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	J	US-			
	K	US-			
	L	US-			
	M	US-			

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NON-PATENT DOCUMENTS

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	U	Li, S.; Freidhoff, C.B.; Young, R. M.; Ghodssi, R. "Fabrication of micronozzles using low-temperature wafer-level bonding with SU-8." Journal of Micromechanics Microengineering. 2003, Vol. 13, pp.732-738.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.